IN THE CLAIMS:

Please amend the claims as follows:

- 1. *(currently amended)* A method for analysing connection conditions between an integrated circuit package and a circuit board, comprising the steps of:
 - wherein electrically coupling said integrated circuit package is electrically coupled to said circuit board by coupling elements, [[and]]
 - wherein mechanically connecting said integrated circuit package is mechanically connected with said circuit board by support elements,
 characterised in that
 - electrically connecting at least two of said support elements with each other are
 electrically connected to each other on the side of the integrated circuit package,
 - picking-off physical values are picked-off from between said support elements, and
 - evaluating said physical values are evaluated to determine the condition of said
 connection between said integrated circuit package and said circuit board. mechanical
 properties if said support,
 - concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
- 2. (original) The method of claim 1, wherein electrical values are picked-off from said support elements.
- 3. (original) The method of claim 1, wherein electrical resistance and/or electrical current and/or voltage within said support elements is picked-off.
- 4. (original) The method of claim 1, wherein mechanical values are picked-off from said support elements.

- 5. (original) The method of claim 1, wherein mechanical values are picked-off from said support elements using a strain gauge.
- 6. (cancelled)
- 7. (original) The method of claim 1, wherein said connection condition is determined in intervals.
- 8. (original) The method of claim 1, wherein said determined connection conditions are stored.
- 9. *(original)* The method of claim 1, wherein in case a poor connection condition is determined, a error message is generated.
- 10. (original) The method of claim 9, wherein said error message is presented on a user interface.
- 11. (original) The method of claim 9, wherein said error message is stored.
- 12. *(original)* The method of claim 9, wherein said error message is read out from a storage and used for maintenance.
- 13. *(currently amended)* A system for analysing connection conditions between an integrated circuit package and a circuit board, comprising:
 - coupling elements coupling said integrated circuit package electrically to said circuit board, and
 - support elements connecting said integrated circuit package mechanically with said

- circuit board, characterised by wherein said system further comprises:
- means for electrically connecting at least two of said support elements with each other on the side of the integrated circuit package,
- measuring means arranged at said support elements to pick off for picking-off physical values between [[from]] said support elements, and
- evaluation means <u>for</u> evaluating said physical values to determine the condition of said connection between said integrated circuit package and said circuit board <u>mechanical</u> properties of said support elements, and for concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
- 14. *(original)* The system of claim 13, wherein said support elements are arranged between said circuit board and said integrated circuit package.
- 15. (original) The system of claim 13, wherein said support elements are solder pads.
- 16. (original) The system of claim 13, wherein said support elements are arranged adjacent to said coupling elements.
- 17. *(original)* The system of claim 13, wherein said support elements are arranged semicircular along said coupling elements.
- 18. *(original)* The system of claim 13, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
- 19. *(original)* The system of claim 13, wherein said integrated circuit package is a chip scale package or a chip size package.

- 20. (original) The system claim 13, wherein said measuring means provide picking-off electrical conditions of said support elements.
- 21. *(original)* The system claim 13, wherein said measuring means provide picking-off mechanical conditions of said support elements.
- 22. (original) The system of claim 13, wherein storage means are comprised to store said picked-off physical values.
- 23. (original) The system of claim 13, wherein said evaluation means compare said picked-off physical values with comparative values to determine connection condition.
- 24. *(original)* The system of claim 13, wherein said evaluation means provide an error message in case a poor connection condition is determined.
- 25. (original) The system of claim 13, wherein said error message is stored within said storage means.
- 26. (original) The system of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.
- 27. (original) Consumer electronic device, in particular a mobile phone, comprising a system of claim 13.
- 28. *(original)* Computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.

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29. (original) Computer program product comprising a computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.